

UVD5271

Polymer Thick Film

Description

UVD5271 is an UV curable solder mask, overcoat, or dielectric designed for rigid substrates. UVD5271 offers rapid curing combined with outstanding adhesion and resistance to solvents, moisture, and the soldering process. It is less sensitive to surface cleanliness than other UV curable materials. It offers excellent electrical and environmental integrity after soldering and cleaning, and outstanding line definition, typically >8 mils. Heraeus also offers a series of compatible, thermally cured conductors.

Key Features

- REACH and ROHS compliant
- High adhesion to many industry common substrates
- Excellent chemical and solder resistance
- High insulating resistance and breakdown voltage



This picture does not show the packaging of UVD5271 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms

Typical Properties

| | |
|-----------------------|---|
| Viscosity | 10 – 30 Kcps; Brookfield HBT spindle #14 @ 50 RPM, 25°C |
| Color | Dark Blue |
| 95% Max Particle Size | <10 µm, hegman |

Recommended Processing Guide

| | |
|---------------------|--|
| Printing Parameters | 250-280 mesh screen recommended .5 mil emulsion .02" snap-off distance |
| Drying Temperature | 200°C |
| Film Thickness | 12-25 µm DFT |
| Recommended Thinner | RV-825 |
| Paste Compatibility | Compatible with all PriElex products |

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Warranty

6 months

Storage

Ambient storage, mix well prior to use

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